Texas Instruments Inc. (DUNS# 00-732-1904) Supplier Name:

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

05/06/2022

Details for "TLC4502CDR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLC4502CDR	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D 8	3.91x4.9x1.58	85.1

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

Component Information

				Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm		
Bond Wire									
Copper and Its Alloys	Copper	7440-50-8	0.024927	100	1000000	0.029293	293		
Sub-Total			0.024927	100	1000000	0.029293	293		
Die Attach Adhesive									
Precious Metals	Silver	7440-22-4	0.729599	79.999978	800000	0.857375	8574		
Thermoplastics	Ероху	85954-11-6	0.1824	20.000022	200000	0.214344	2143		
Sub-Total			0.911999	100	1000000	1.07172	10717		
Lead Frame									
Copper and Its Alloys	Copper	7440-50-8	24.416166	97.425006	974250	28.692228	286922		
Copper and Its Alloys	Iron	7439-89-6	0.601476	2.4	24000	0.706814	7068		
Copper and Its Alloys	Phosphorus	7723-14-0	0.003759	0.014999	150	0.004417	44		
Copper and Its Alloys	Tin	7440-31-5	0.007518	0.029998	300	0.008835	88		
Copper and Its Alloys	Zinc	7440-66-6	0.025061	0.099998	1000	0.02945	294		
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.007518	0.029998	300	0.008835	88		
Sub-Total			25.061498	100	1000000	29.450579	294506		
Lead Frame Plating									
Nickel and Its Alloys	Nickel	7440-02-0	0.036621	95.121951	951220	0.043035	430		
Precious Metals	Gold	7440-57-5	0.0003	0.779241	7792	0.000353	4		
Precious Metals	Palladium	7440-05-3	0.001578	4.098808	40988	0.001854	19		
Sub-Total			0.038499	100	1000000	0.045241	452		
Mold Compound									
Other Inorganic Materials	Fused Silica	60676-86-0	49.348976	88	880000	57.991582	579916		
Other Plastics and Rubber	Carbon Black	1333-86-4	0.168235	0.3	3000	0.197698	1977		
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.308431	0.55	5500	0.362447	3624		
Thermoplastics	Ероху	85954-11-6	6.25274	11.150001	111500	7.347798	73478		
Sub-Total			56.078382	100	1000000	65.899525	658995		
Semiconductor Device									
Ceramics / Glass	Doped Silicon	7440-21-3	2.981487	100	1000000	3.503642	35036		
Sub-Total			2.981487	100	1000000	3.503642	35036		
Total			85.096792	·	_	100	1000000		

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSis or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Tl and Tl suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by Tl. The material content information is provided by Tl "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/06/2022

ROHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.